L Number	Hits	Search Text	DB	Time stamp
1	330		USPAT;	2003/05/16 14:10
		board)) and (thermal adj vias)	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
2	505		USPAT;	2003/05/16 14:10
		board)) and (thermal adj (pad vias))	US-PGPUB;	
			EPO; JPO;	
			DERWENT	0000/05/16 14 11
3	181		USPAT;	2003/05/16 14:11
		board)) and (thermal adj (pad vias))) and	US-PGPUB;	
		(semiconductor near1 (package packaging	EPO; JPO; DERWENT	
	220	device))	USPAT;	2003/05/16 14:12
4	238	((pcb substrate (printed adj circuit adj board)) and (thermal adj (pad vias))) and	US-PGPUB;	2003/03/10 14.12
		(semiconductor chip IC) and (heat adj	EPO; JPO;	
		sink)	DERWENT	
5	181		USPAT;	2003/05/16 14:13
		board)) and (thermal adj (pad vias))) and	US-PGPUB;	2000, 00, 20 2002
		(semiconductor nearl (package packaging	EPO; JPO;	
		device))) and (semiconductor chip IC)	DERWENT	
6	102	_ · · · · · · · · · · · · · · · · · · ·	USPAT;	2003/05/16 14:13
		board)) and (thermal adj (pad vias))) and	US-PGPUB;	
		(semiconductor nearl (package packaging	EPO; JPO;	
		device))) and (sealing encapsulating	DERWENT	
		encapsulant encapsulated)		
7	1	5942795.URPN.	USPAT	2003/05/16 14:32
8	6	,	USPAT	2003/05/16 14:33
		"5777387" "5789810" "5854512").PN.		

L Number	Hits	Search Text	DB	Time stamp
85	51	"5835988"	USPAT;	2003/05/16 15:20
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	0000 405 41 5 45 55
86	28	"5986209"	USPAT;	2003/05/16 15:20
			US-PGPUB;	
			EPO; JPO;	
	4.1	HEEE 400 CH	DERWENT	2003/05/16 15:20
87	41	"5554886"	USPAT; US-PGPUB;	2003/03/18 13.20
			EPO; JPO;	
]			DERWENT	
88	15	"6002167"	USPAT;	2003/05/16 15:20
00	15	0002107	US-PGPUB;	2000, 00, 20 20120
			EPO; JPO;	
			DERWENT	
89	26	"5760471"	USPAT;	2003/05/16 15:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
90	124	"5835988" "5986209" "5554886" "6002167"	USPAT;	2003/05/16 15:22
		"5760471"	US-PGPUB;	
			EPO; JPO;	
		6404046 ***	DERWENT	2002/05/16 15 22
91	1	6404046.URPN.	USPAT	2003/05/16 15:33
92	41	("3838984" "4159221" "4398235"	USPAT	2003/05/16 15:33
		"4833568" "4956694" "4996587"		
		"5068713" "5230759" "5258094" "5266834" "5332864" "5381039"		
		"5266834" "5332864" "5381039" "5381047" "5394010" "5414300"		
		"5435057" "5455387" "5521429"		
		"5587341" "5594275" "5625221"		
		"5677569" "5715147" "5742007" .		
		"5760471" "5835988" "5852320"		
		"5859471" "5877043" "5880403"		
		"5950074" "5962810" "5977613"		
		"5986209" "6114221" "6130115"		
	ļ	"6143981" "6225146" "6242281"		
		"6281568" "6404046").PN.		
-	30061	((folded nearl flexible nearl substrate)	USPAT;	2002/04/08 07:18
		((flexible ner1 tape) near3 around))	US-PGPUB;	
			EPO; JPO;	
		4446 3 3 3 3 4 63 43 3 4 6 3 4 3 4 4 5	DERWENT	2002/02/25 07:07
-	15	(((folded near1 flexible near1 substrate)	USPAT;	2002/02/25 07:07
		((flexible near1 tape) near3 around))) and	US-PGPUB;	
		(bump ball)	EPO; JPO; DERWENT	
_	128	(((folded nearl flexible nearl substrate)	USPAT;	2002/02/25 07:10
_	128	((flexible near1 tape) near3 around))) not	US-PGPUB;	
		((((folded near1 flexible near1 substrate)	EPO; JPO;	
		((flexible near1 tape) near3 around))) and	DERWENT	
		(bump ball))	Ī	
_	35		USPAT;	2002/02/25 07:13
		((flexible near1 tape) near3 around))) and	US-PGPUB;	
		chips	EPO; JPO;	
	1	•	DERWENT	
-	41	(((folded nearl flexible nearl substrate)	USPAT;	2002/08/09 13:15
		((flexible near1 tape) near3 around))) and	US-PGPUB;	
		(chips die (integrated adj circuit))	EPO; JPO;	
			DERWENT	2002/02/02 10:01
-	144		USPAT;	2002/03/22 10:01
1		((flexible near1 tape) near3 around))	US-PGPUB;	
			EPO; JPO;	
		11624611411	DERWENT USPAT;	2002/03/22 10:12
-	3	"6246114"	US-PGPUB;	2002/03/22 10:12
	1		EPO; JPO;	
			DERWENT	
	L	<u></u>	1 241111111	l

33					
- 33 "5394303"	-	19	"5818107"	USPAT;	2002/03/22 10:14
S33 "5394303" S2587; USPAT; U					
33					
Solution		33	"5204202"		2002/03/22 10:17
FUKAZAWA-NORIO	-	33	3334303	· ·	2002/03/22 10.1/
DERMENT USPAT;					
SAWAHARA-KOICH SPG; JPG; JPG; JPG; JPG; JPG; JPG; JPG; J	1				
Section Sect	_	30	FUKAZAWA-NORIO	USPAT;	2002/03/22 10:30
RAWAHARA-KOICHI		- '		US-PGPUB;	
Section					
Section				- '	
## ## ## ## ## ## ## ## ## ## ## ## ##	-	8	KAWAHARA-KOICHI	-	2002/03/22 10:30
A8					
48				· · · · · · · · · · · · · · · · · · ·	
145		ΛΩ	"5394303" "5818107" "6246114"		2002/03/22 10:58
(((flexible nearl tape) near3 around)) (((flexible nearl tape) near3 around)) (((flexible nearl flexible nearl substrate)) ((((flexible nearl flexible nearl substrate)) ((((flexible nearl tape) near3 around))) and ((((flexible nearl tape) near3 around))) and ((((((flexible nearl tape) near3 around))) and (((((flexible nearl tape) near3 around))) and ((((((flexible nearl tape) near3 around))) and ((((((flexible nearl tape) nearl substrate))) (((((((flexible nearl tape) nearl substrate)))) ((((((((((flexible nearl substrate)))))))))))))))))))))))))))))))))))	_				The state of the s
12		113	, ,		
12			((2200000000000000000000000000000000000		
(((flexible nearl tape) near3 around))) and (bump ball) and (rigid reinforcs4) (((flexible mearl flexible nearl substrate) ((flexible nearl tape) near3 around))) and (bump ball) (((((folded nearl flexible nearl tape) near3 around))) and (bump ball)) not (((((folded nearl flexible nearl tape) near3 around))) and (bump ball)) not ((((folded nearl flexible nearl tape) near3 around))) and (chip device die) ((((folded nearl flexible nearl substrate) ((flexible nearl tape) near3 around))) and (chip device die)) and (polyimide polymeric polymer rubber) (((((folded nearl flexible nearl substrate) ((((flexible nearl tape) near3 around))) and (polyimide polymeric polymer rubber) ((((((flexible nearl tape) near3 around))) and (polyimide polymeric polymer rubber) (((((((flexible nearl tape) near3 around))) and (polyimide polymeric polymer rubber) ((((((((flexible nearl flexible nearl substrate) ((((((((((((((((((((((((((((((((((((DERWENT	
Chump ball) and (rigid reinforc\$4) Cherkent Colded near1 flexible near1 substrate) Colded near1 flexible near3 around)) and (climp ball) Colded near1 flexible near1 substrate) Colded near1 flexible near1 substrate) Colded near1 substrate) Colded near1 substrate) Colded near1 flexible near2 substrate) Colded near3 around)) and (chip device die) Colded near3 around) Colded near3 around	-	12	(((folded nearl flexible nearl substrate)		2002/08/09 13:14
Service Comparison Compar					
15			(bump ball) and (rigid reinforc\$4)		
(((flexible nearl tape) near3 around))) and (bump ball) ((((folded nearl flexible nearl substrate) ((flexible nearl tape) near3 around))) and (bump ball)) not ((((flexible nearl flexible nearl flexible nearl substrate) ((flexible nearl tape) near3 around))) and (bump ball) and (rigid reinforcs4)) ((((folded nearl flexible nearl substrate) ((flexible nearl tape) near3 around))) and (bump ball) and (rigid reinforcs4)) (((((folded nearl flexible nearl substrate) ((flexible nearl tape) near3 around))) and (chip device die)) and (polyimide polymeric polymer rubber) (((((folded nearl flexible nearl tape) near3 around))) and (bump ball) and (polyimide polymeric polymer rubber) (((flexible nearl flexible nearl substrate) ((flexible nearl flexible nearl substrate) (flexible nearl substrate) (flex		1.5	///folded poar1 flowible rear1 substrate)		2002/04/08 07.24
Chump ball)	-	12			2002/04/00 07.24
- 3 ((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball)) not ((((folded near1 flexible near1 tape) near3 around))) and (bump ball)) and (bump ball) and (rigid reinforcs4)) - 88 (((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (chip device die) - 41 ((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (chip device die) and (polyimide polymeric polymer rubber) (((flexible near1 flexible near1 substrate) ((flexible near1 flexible near1 substrate) (flexible near1 flexible near1 substrate) (flexible near1 flexible near1 substrate) (flexible near1 flexible near1 substrate) (SPAT; US-PGPUB; EPO; JPO; DERWENT ((flexible near1 flexible near1 substrate)) (DERWENT (US-PGPUB; EPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO; J			1 ' '		
C(((folded nearl flexible nearl substrate) (((flexible nearl tape) near3 around))) and (bump ball)) not ((((folded nearl flexible nearl tape) near3 around))) and (bump ball)) and (bump ball) and (rigid reinforc\$4))			(bump ball)		
((flexible nearl tape) near3 around)) and (bump ball)) not (((folded nearl flexible nearl substrate)) ((flexible nearl tape)) near3 around))) and (bump ball) and (rigid reinforcs4)) - 88 ((flexible nearl flexible nearl substrate) ((flexible nearl tape) near3 around))) and (chip device die) - 41 ((((folded nearl flexible nearl substrate)) ((flexible nearl tape) near3 around))) and (chip device die)) and (polyimide polymeric polymer rubber) (((((folded nearl flexible nearl substrate))) and (polyimide polymeric polymer rubber) ((((flexible nearl flexible nearl substrate))) and (chip device die)) and (polyimide polymeric polymer rubber)) not ((((folded nearl flexible nearl substrate))) (((flexible nearl flexible nearl substrate))) (((floded nearl flexible nearl substrate))) (((floded nearl flexible nearl substrate))) (((floded nearl flexible nearl substrate))) ((flexible nearl flexible nearl substrate))) ((flexible nearl flexible nearl substrate))) ((flexible nearl flexible nearl substrate)) ((flexible nearl substrate))) ((flexible nearl flexible nearl substrate))) (folded nearl flexible nearl substrate)) (flexible nearl substrate)) (_	3	((((folded near1 flexible near1 substrate)		2002/04/08 07:24
(bump ball)) not ((((folded nearl flexible nearl substrate) (nearl substrate)) ((flexible nearl tape) near3 around))) and (bump ball) and (rigid reinforcs41) 88 (((folded nearl flexible nearl substrate) ((flexible nearl tape) near3 around))) and (chip device die) ((((folded nearl flexible nearl substrate)) ((((flexible nearl tape) near3 around))) and (chip device die)) and (polyimide polymeric polymer rubber) ((((((folded nearl flexible nearl substrate))) and (polyimide polymeric polymer rubber)) not ((((folded nearl flexible nearl substrate))) and (polyimide polymeric polymer rubber)) not ((((folded nearl flexible nearl substrate))) and (bump ball)) and (bump ball)) and (bump ball)) 18 (((folded nearl flexible nearl substrate)) (((flexible nearl flexible nearl substrate))) and (((((folded nearl flexible nearl substrate)))) pot ((((folded nearl flexible nearl substrate))) and (((((folded nearl flexible nearl substrate)))) pot (((((folded nearl flexible nearl substrate)))) pot ((((folded nearl flexible nearl substrate))) pot (((((folded nearl flexible nearl substrate))) pot ((((folded nearl flexible nearl substrate))) pot ((((folded nearl substrate)))) pot ((((flexible nearl substrate))) pot ((((flexible nearl substrate))) pot ((((flexible nearl substrate)))) pot (((((flexible				US-PGPUB;	
near3 around)) and (bump ball) and (rigid reinforc\$4))				EPO; JPO;	
reinforcs4)) (((folded nearl flexible nearl substrate) ((flexible nearl tape) near3 around))) and ((chip device die) (((((folded nearl flexible nearl substrate)) ((flexible nearl tape) near3 around))) and ((chip device die)) and (polyimide polymeric polymer rubber) ((((((folded nearl flexible nearl substrate)) (((((folded nearl flexible nearl substrate)) ((flexible nearl tape) near3 around))) and ((chip device die)) and (polyimide polymeric polymer rubber)) not ((((folded nearl flexible nearl substrate)) (((flexible nearl tape) near3 around))) and (bump ball)) - 23 ((folded nearl flexible nearl substrate)) (((folded nearl flexible nearl substrate)) (((folded nearl flexible nearl substrate))) (((folded nearl substrate))) (((folded nearl flexible nearl substrate))) (((folded nearl substrate))) (((folded nearl substrate))) (((folded nearl substrate))) (((folded nearl substrate))) ((folded nearl substrate)) ((fold				DERWENT	
Second Content Conte					
((flexible nearl tape) near3 around))) and (chip device die) (((((folded nearl flexible nearl substrate) ((flexible nearl tape) near3 around))) and (chip device die)) and (polyimide polymeric polymer rubber) (((((folded nearl flexible nearl substrate) ((flexible nearl flexible nearl substrate) (((((folded nearl flexible nearl substrate) ((((((folded nearl flexible nearl substrate) ((((((((folded nearl flexible nearl substrate) ((((((((((((((((((((((((((((((((((((0000/01/00 07 05
(chip device die) ((i) ((i) device die) ((i) ((i) ded nearl flexible nearl substrate) ((i) and (polyimide polymeric polymer rubber) ((i) ((i) ded nearl flexible nearl substrate) ((i) (i) ded nearl flexible nearl substrate) ((i) ded nearl substrate) ((i) ded nearl flexible nearl substrate) ((i) ded nearl substrate) ((i) dewind nearl substrate)	-	88		· ·	2002/04/08 07:25
DERWENT ((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (chip device die)) and (polyimide polymeric polymer rubber) (((((folded near1 flexible near1 substrate) (((((folded near1 flexible near1 substrate) (flexible near1 tape) near3 around))) and (polyimide polymeric polymer rubber)) not ((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball)) (folded near1 flexible near1 substrate) ((folded near1 flexible near1 substrate)) ((((folded near1 flexible near1 substrate))) pot ((((folded near1 substrate))) pot ((((folded near1 flexible near1 substrate))) pot ((((folded near1 substrate))) pot ((((folded near1 substrate))) pot ((((folded near1 substrate)))) pot (((((folded near1 substrate)))) pot (((((folded near1 substrate)))) pot (((((((((((((((((((((((((((((((((((
- 41 ((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (chip device die)) and (polyimide polymeric polymer rubber) (((((folded near1 flexible near1 substrate)) (((folded near1 flexible near1 substrate)) ((flexible near1 tape) near3 around))) and (bump ball)) - 23 ((folded near1 flexible near1 substrate)) ((flexible near1 flexible near1 substrate)) ((flexible near1 flexible near1 substrate)) not (((folded near1 flexible near1 substrate))) not (((folded near1 substrate))) not (((folded near1 flexible near1 substrate))) not (((folded near1 substrate))) not (((flexible near1 substrate))) not (((folded near1 substrate))) not (((flexible near1 substrate))) not ((flexible near1 substrate))) not ((flexible near1 substrate))) not ((flexible near1 substrate))) not ((flexible near1 substrate)) not (fl			(chip device die)		
((flexible near1 tape) near3 around))) and (chip device die)) and (polyimide polymeric polymer rubber) (((((folded near1 flexible near1 substrate))) and (polyimide polymeric polymer rubber)) (((((folded near1 flexible near1 substrate))) and (polyimide polymeric polymer rubber)) not ((((folded near1 flexible near1 substrate))) and (bump ball)) (folded near1 flexible near1 substrate)) (flexible near1 substrate)) (flexible near1 substrate) (flexible near1 substrate) (flexible near1 substrate) (flexible near1 substrate) (folded near1 substrate) (flexible near1 substrate)		41	((((folded near1 flexible near1 substrate)		2002/04/08 07:26
Cchip device die) and (polyimide polymeric polymer rubber) DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; U		1.1			
31	ļ			EPO; JPO;	
substrate) ((flexible near1 tape) near3 around))) and (chip device die)) and (polyimide polymeric polymer rubber)) not ((((floxible near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball)) - 23 ((folded near1 flexible near1 substrate) - 18 ((folded near1 flexible near1 substrate)) ((((folded near1 flexible near1 substrate))) ((((folded near1 flexible near1 substrate))) ((((folded near1 flexible near1 substrate))) (((((folded near1 flexible near1 substrate)))) (((((folded near1 flexible near1 substrate)))) ((((((folded near1 flexible near1 substrate))))) ((((((((((((((((((((((((((((((((polymeric polymer rubber)	DERWENT	
around))) and (chip device die)) and (polyimide polymeric polymer rubber)) not (((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball)) 23 (folded near1 flexible near1 substrate) ((folded near1 flexible near1 substrate)) (folded near1 substrate) (flexible near1 subst	-	31	((((folded nearl flexible nearl		2002/04/08 07:26
(polyimide polymeric polymer rubber)) not ((((folded near1 flexible near1 substrate) ((flexible near1 tape) near3 around))) and (bump ball)) - 23 (folded near1 flexible near1 substrate) ((folded near1 flexible near1 substrate)) ((flexible near1 tape) near3 (substrate) ((flexible near1 tape) near3 (substrate) (flexible near1 tape) (folded near1 substrate) (flexible near1 tape) (folded near1 substrate) (flexible near1 tape) (folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4) 240 ((folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4) 240 ((folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4) 240 ((folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4) 240 (folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4) 240 (folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4)) 240 (folded near1 substrate) (flexible near1 tape) near3 tape) and (bump ball) and (rigid reinforc\$4)) 240 (folded near1 substrate) (flexible near1 tape) near3 tape) deared and (bump ball) and (rigid reinforc\$4)					
((((folded nearl flexible nearl substrate) ((flexible nearl tape) near3 around))) and (bump ball)) (folded nearl flexible nearl substrate) 18 ((folded nearl flexible nearl substrate) USPAT; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO;			around))) and (chip device die)) and		
((flexible near1 tape) near3 around))) and (bump ball)) (folded near1 flexible near1 substrate) 18 ((folded near1 flexible near1 substrate)) USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; Substrate) ((flexible near1 tape) near3 around))) and (bump ball)) 5921 folded near1 substrate) (flexible near1 USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; J			(polyimide polymeric polymer rubber)) not	DERWENT	
- 23 (bump ball)) (folded nearl flexible nearl substrate) - 18 ((folded nearl flexible nearl substrate)) not (((folded nearl flexible nearl substrate)) not (((folded nearl flexible nearl substrate)) substrate) ((flexible nearl tape) near3 around))) and (bump ball)) - 5921 folded nearl substrate) (flexible nearl tape - 398 (folded nearl substrate) (flexible nearl tape) and (bump ball) and (rigid reinforc\$4) - 240 ((folded nearl substrate) (flexible nearl tape) and (bump ball) and (rigid reinforc\$4)) and (chip die (integrated adj reinforc\$4)) and (chip die (integrated adj USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO;				†	
- 23 (folded near1 flexible near1 substrate) USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO		}			
- 18 ((folded near1 flexible near1 substrate)) 18 ((folded near1 flexible near1 substrate)) 18 ((folded near1 flexible near1 substrate)) 19 ((folded near1 flexible near1 tape) near3 substrate) ((flexible near1 tape) near3 saround))) and (bump ball)) 10 (folded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) JPO; DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) JPO; DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid tape) and (bump ball) and (rigid tape) and (chip die (integrated adj tape) JPO; DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 substrate) (flexible near1 tape) DERWENT USPAT; 10 (Ifolded near1 tape) DERWENT USPAT; 10 (If	_	23		USPAT;	2002/04/08 07:27
- 18 ((folded near1 flexible near1 substrate)) not ((((folded near1 flexible near1 substrate)) not ((((folded near1 flexible near1 substrate)) substrate) ((flexible near1 tape) near3 around))) and (bump ball)) - 5921 folded near1 substrate) (flexible near1 tape - 398 (folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4) - 240 ((folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4)) - 240 ((folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4)) and (chip die (integrated adj EPO; JPO;					
- 18 ((folded near1 flexible near1 substrate)) not ((((folded near1 flexible near1 substrate)) not ((((folded near1 flexible near1 substrate) near3 substrate) ((flexible near1 tape) near3 substrate) (flexible near1 tape) near3 substrate) (flexible near1 tape) DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; tape) and (bump ball) and (rigid reinforc\$4) - 240 ((folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid tape) and (bump ball) and (rigid reinforc\$4)) and (chip die (integrated adj EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB					
not ((((folded nearl flexible nearl substrate) (flexible nearl tape) near3 around))) and (bump ball)) 5921 folded nearl substrate) (flexible nearl tape) 1		1			0000/01/00 05 05
substrate) ((flexible near1 tape) near3 around))) and (bump ball)) 5921 folded near1 substrate) (flexible near1 tape (folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4) 240 ((folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4) 240 ((folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4) 240 ((folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4) 240 (folded near1 substrate) (flexible near1 tape) and (bump ball) and (rigid reinforc\$4) 25002/08/09 13:12 25002/08/09 13:14 25002/08/09 13:21 25002/08/09 13:21 25002/08/09 13:21 25002/08/09 13:21	-	18		1	2002/04/08 07:28
around))) and (bump ball)) folded nearl substrate) (flexible nearl USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; Teinforc\$4) and (bump ball) and (rigid US-PGPUB; reinforc\$4)) and (chip die (integrated adj EPO; JPO;		1	, , , ,		
- 5921 folded near1 substrate) (flexible near1 tape USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; U		1			:
tape tape US-PGPUB; EPO; JPO; DERWENT USPAT; tape) and (bump ball) and (rigid reinforc\$4) US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; tape) and (bump ball) and (rigid reinforc\$4)) and (chip die (integrated adj EPO; JPO;	_	5921			2002/08/09 13:12
- 398 (folded near1 substrate) (flexible near1 USPAT; tape) and (bump ball) and (rigid reinforc\$4) - 240 ((folded near1 substrate) (flexible near1 USPAT; tape) and (bump ball) and (rigid tape) and (bump ball) and (rigid reinforc\$4)) and (chip die (integrated adj EPO; JPO; JPO;		3,21			=====================================
- 398 (folded near1 substrate) (flexible near1 USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; reinforc\$4) and (chip die (integrated adj EPO; JPO;					
tape) and (bump ball) and (rigid US-PGPUB; reinforc\$4) - 240 ((folded near1 substrate) (flexible near1 USPAT; tape) and (bump ball) and (rigid US-PGPUB; reinforc\$4)) and (chip die (integrated adj EPO; JPO;					
reinforc\$4) - 240 ((folded near1 substrate) (flexible near1 USPAT; tape) and (bump ball) and (rigid reinforc\$4)) and (chip die (integrated adj EPO; JPO;	-	398		_ ·	2002/08/09 13:14
- 240 ((folded near1 substrate) (flexible near1 USPAT; 2002/08/09 13:21 tape) and (bump ball) and (rigid reinforc\$4)) and (chip die (integrated adj EPO; JPO;				· ·	
- 240 ((folded near1 substrate) (flexible near1 USPAT; tape) and (bump ball) and (rigid US-PGPUB; reinforc\$4)) and (chip die (integrated adj EPO; JPO;	1		reinforc\$4)		
tape) and (bump ball) and (rigid US-PGPUB; reinforc\$4)) and (chip die (integrated adj EPO; JPO;		1	(/Solded moor1 substrate) /flowible moor1		2002/08/09 13:21
reinforc\$4)) and (chip die (integrated adj EPO; JPO;	-	240			2002/00/09 13:21
circuit) (semiconductor adi element)) DERWENT	1		reinforc\$4)) and (chip die (integrated adi	l .	
			circuit) (semiconductor adj element))	l '	

-	75	(((folded nearl substrate) (flexible nearl tape) and (bump ball) and (rigid reinforc\$4)) and (chip die (integrated adj circuit) (semiconductor adj element))) and (second near3 (chip die (integrated adj circuit) (semiconductor adj element)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/09 13:30
-	17	"5805422"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/10 08:36
-	15 6	5805422.URPN. ("3427715" "4922059" "5148265" "5148266" "5229916" "5394303").PN.	USPAT USPAT	2003/03/10 08:39 2003/03/10 08:39
-	7 5	6225688.URPN. ("4982265" "5046238" "5334875"	USPAT USPAT	2003/03/18 12:42 2003/03/18 12:45
-	12 5	("3039177" "3467892" "4628408"	USPAT USPAT	2003/03/18 12:45 2003/03/18 14:09
	57 41305	"4833568" "5289346").PN. 5289346.URPN. semiconductor and (stacking stacked)	USPAT USPAT;	2003/03/18 14:09 2003/03/18 14:37
_	35232	(semiconductor and (stacking stacked)) and	US-PGPUB; EPO; JPO; DERWENT USPAT;	2003/03/18 14:38
_	215	<pre>(method process) ((semiconductor and (stacking stacked))</pre>	US-PGPUB; EPO; JPO; DERWENT USPAT;	2003/03/18 14:42
		and (method process)) and ((plexible nearl (tape substrate)) (bonding near tape))	US-PGPUB; EPO; JPO; DERWENT	
-	63	<pre>(((semiconductor and (stacking stacked)) and (method process)) and ((plexible near1 (tape substrate)) (bonding near tape))) and (bending bended)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:40
-	23	((plexible near1 (tape substrate)) (bonding near tape)) with (bending bended)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:41
-	2	<pre>(((semiconductor and (stacking stacked)) and (method process)) and ((plexible near1 (tape substrate)) (bonding near tape))) and (((plexible near1 (tape substrate)) (bonding near tape)) with (bending bended))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:41
_	248	((semiconductor and (stacking stacked)) and (method process)) and (((plexible folded folding) nearl (tape substrate)) (bonding near tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:43
-	16	1	USPAT; US-PGPUB; JPO	2003/03/18 14:43
-	244	(((semiconductor and (stacking stacked)) and (method process)) and (((plexible folded folding) near1 (tape substrate)) (bonding near tape))) not ((US-5805422-\$ or US-5394303-\$ or US-6225688-\$ or US-5776797-\$ or US-5646446-\$ or US-6246114-\$ or US-5818107-\$ or US-6528353-\$ or US-6473308-\$ or US-6462412-\$ or US-6441476-\$ or US-6300679-\$ or US-6262895-\$ or US-6121676-\$).did. or (US-20010006252-\$).did. or (JP-08222691-\$).did.)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/18 14:43

	,		1	10000/00/100
-	2	("6049123" "6102710").PN.	USPAT	2003/03/18 14:48
-	0	6469377.URPN.	USPAT	2003/03/18 14:49
-	0	6444921.URPN.	USPAT	2003/03/18 14:55
-	44	("3795037" "4271588" "4547834"	USPAT	2003/03/18 14:55
		"4648179" "4664309" "4755417"		
		"4783722" "4800461" "4858077"		<u> </u>
		"4897918" "4954877" "4954878"		
		"5065227" "5100492" "5177594"		į
		"5199163" "5264065" "5306571"		
		"5378306" "5426072" "5428190"		
	ì	"5429879" "5474458" "5478972"		
		"5483421" "5499444" "5530288"	ļ	
		"5544017" "5573428" "5575630"		
i	1	"5590460" "5591519" "5627405"		
		"5659153" "5665650" "5678287"		
		"5682061" "5688584" "5691041"		
		"5745986" "6064576" "6118671"		
		"6191952" "6259037").PN.		1
	0	6344683.URPN.	USPAT	2003/03/18 14:58
1	7	("5377077" "5446620" "5463253"	USPAT	2003/03/18 14:58
-	· '	"5815372" "5933712" "5995379"	OSIAI	2003/03/10 14:50
		"6005292").PN.		
	10	5933712.URPN.	USPAT	2003/03/18 15:00
-	10		USPAT	2003/03/18 15:02
-	3	("5432729" "5466634" "5578516").PN.		2003/03/18 15:02
-	3	("5432729" "5466634" "5578516").PN.	USPAT	2003/03/18 15:08
-	5	6121676.URPN.	USPAT	2003/03/18 15:09
-	12	("5008496" "5229916" "5345205"	USPAT	2003/03/18 15:09
		"5783870" "5790380" "5805422"		
		"6014316" "6061245" "6121676"		
		"6172418" "6177721" "6208521").PN.		0002/02/10 15:00
_	12	6208521.URPN.	USPAT	2003/03/18 15:09
_	0	6486544.URPN.	USPAT	2003/03/18 15:11
-	12	("5159535" "5450283" "5578525"	USPAT	2003/03/18 15:11
		"5646446" "5773882" "5783870"		
		"5949142" "5969426" "6071755"		
		"6075287" "6208521" "6324067").PN.		2002/02/10 15 11
-	12	("5159535" "5450283" "5578525"	USPAT	2003/03/18 15:11
	1	"5646446" "5773882" "5783870"		
		"5949142" "5969426" "6071755"		
		"6075287" "6208521" "6324067").PN.	1	
-	3	6281577.URPN.	USPAT	2003/03/18 15:14
-	17	("4983533" "5006925" "5016138"	USPAT	2003/03/18 15:14
		"5224023" "5313096" "5345205"		
		"5397916" "5448511" "5514907"		
		"5602420" "5604377" "5648684"		
		"5656856" "5754405" "5790380"		
		"6121676" "6208521").PN.		
-	23	5448511.URPN.	USPAT	2003/03/18 15:15
-	4	("3766439" "5117282" "5313416"	USPAT	2003/03/18 15:17
		"5335145").PN.		
-	44	5224023.URPN.	USPAT	2003/03/18 15:19
_	0	6507106.URPN.	USPAT	2003/03/18 15:20
_	2	("5224023" "5646446").PN.	USPAT	2003/03/18 15:20
_	1	"6507095"	USPAT;	2003/04/15 08:13
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	